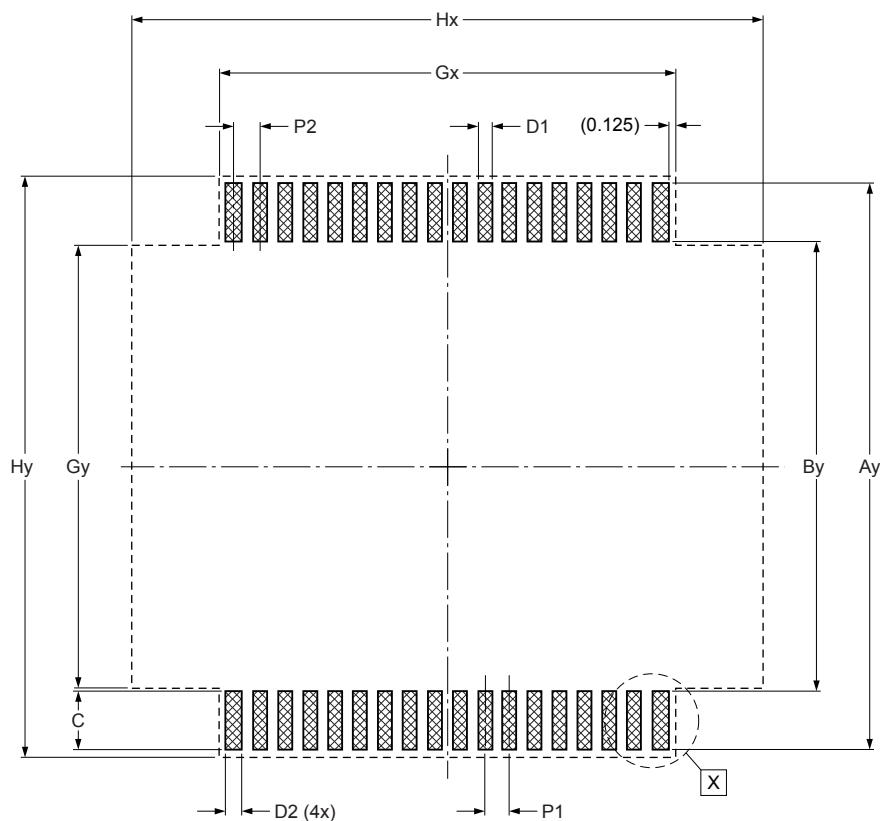


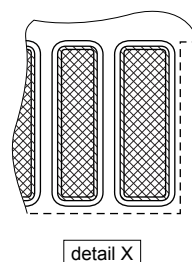


Footprint information for reflow soldering of TSOP36 package

SOT851-2



-  solder paste deposit
-  solder land plus solder paste
- occupied area



DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
0.65	0.65	14.85	11.65	1.6	0.4	0.5	11.9	11.55	16.45	15.15

sot851-2_fr